ABSTRACT OF THE DISCLOSURE

Signal processing is set at step S51. Image information concerning an alignment mark is acquired and calculated from an alignment detecting optical

5 system at step S53. The amount of positional deviation is calculated at step S54 by the signal processing, which was set at step S51, from the alignment-mark image information acquired at step S53. A combination of a shot (position information) and

10 signal processing for which a residual error Ri will be minimized is obtained at step S57, a wafer is positioned in a projection optical system at step S58 by a wafer stage based upon AGA parameters calculated in accordance with the conditions of this minimizing

15 combination, and the pattern on a reticle is transferred to the wafer by exposure at step S59.